



## N-Channel Super Junction Power MOSFET III

## **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

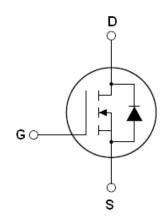
#### **Features**

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

$V_{DS}$	650	V
R <sub>DS(ON)TYP.</sub>	950	mΩ
$I_D$	4	A



Schematic diagram

### **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65T1K2I	TO-251	NCE65T1K2I
NCE65T1K2K	TO-252	NCE65T1K2K





TO-251

TO-252

Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	650	V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	V <sub>G</sub> s	±30	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	4	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	2.5	А
Pulsed drain current (Note 1)	I <sub>DM</sub> (pluse)	16	А
Maximum Power Dissipation(Tc=25℃)	P <sub>D</sub>	41	W
Derate above 25°C		0.328	w/°C
Single pulse avalanche energy (Note2)	Eas	27	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	0.7	Α
Repetitive Avalanche energy , $t_{AR}$ limited by $T_{jmax}$ (Note 1)	E <sub>AR</sub>	0.1	mJ



# NCE65T1K2K,NCE65T1K2I

Parameter	Symbol	Value	Unit
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55+150	°C

#### Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	3.0	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

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Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			50	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	3		4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2A		950	1100	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>Iss</sub>	\/ -50\/\/ -0\/		304		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz		18		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVIDZ		0.6		pF
Total Gate Charge	Qg	\/ -400\/   -40		8.8	12	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =480V, $I_{D}$ =4A, $V_{GS}$ =10V		2.3		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		4		nC
Switching times			•			
Turn-on Delay Time	t <sub>d(on)</sub>			8		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =380V, $I_{D}$ =2.5A,		4		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=5\Omega,V_{GS}=10V$		52	70	nS
Turn-Off Fall Time	t <sub>f</sub>			9	18	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T -25°C			4	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			16	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =4A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			200		nS
Reverse Recovery Charge	Q <sub>rr</sub>	Tj=25°C,I <sub>F</sub> =2A,di/dt=100A/μs		0.6		uC
Peak reverse recovery current	I <sub>rrm</sub>			6		Α
		·				

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V,  $R_G$ =25 $\Omega$ 

V1.0





### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

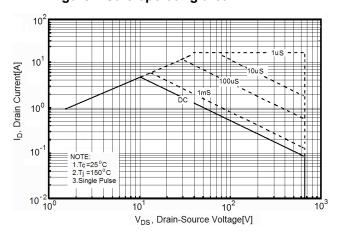


Figure 2. Source-Drain Diode Forward Voltage

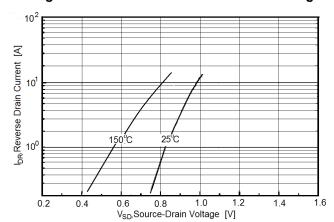


Figure 3. Output characteristics

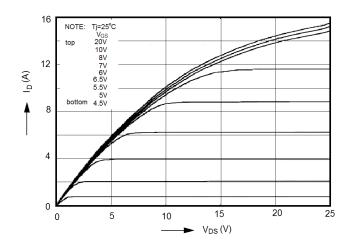


Figure 4. Transfer characteristics

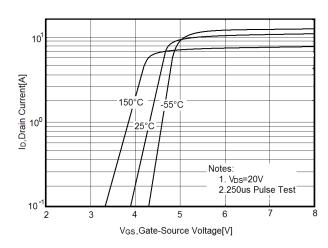


Figure 5. Static drain-source on resistance

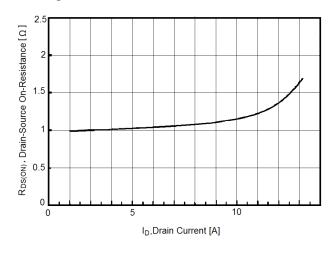
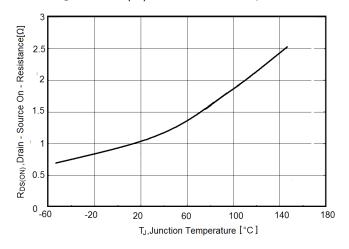


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature





## NCE65T1K2K,NCE65T1K2I

Figure 7.  $BV_{DSS}$  vs Junction Temperature

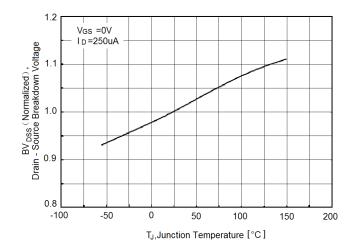


Figure 8. Maximum I<sub>D</sub> vs Junction Temperature

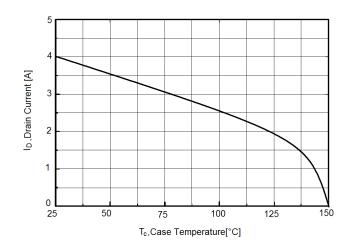


Figure 9. Gate charge waveforms

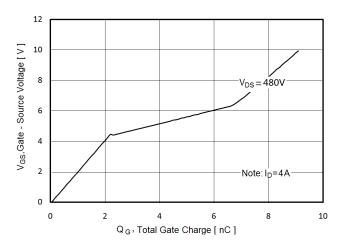


Figure 10. Capacitance

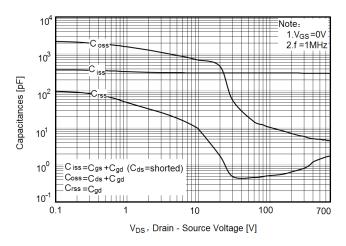
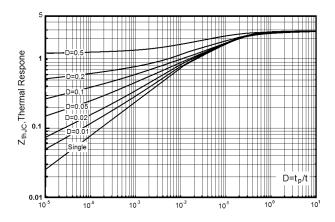


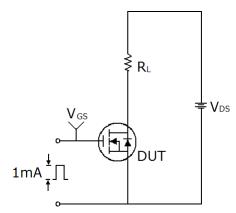
Figure 11. Transient Thermal Impedance

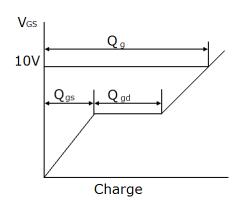




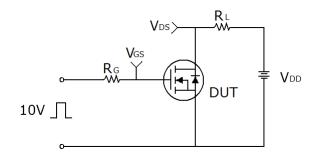
## **Test circuit**

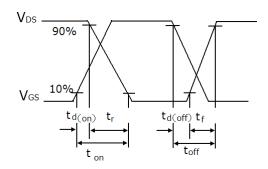
### 1) Gate charge test circuit & Waveform



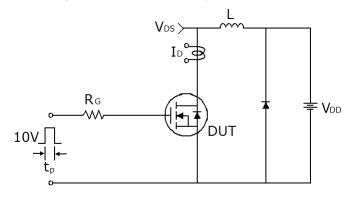


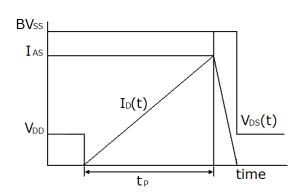
## 2) Switch Time Test Circuit:





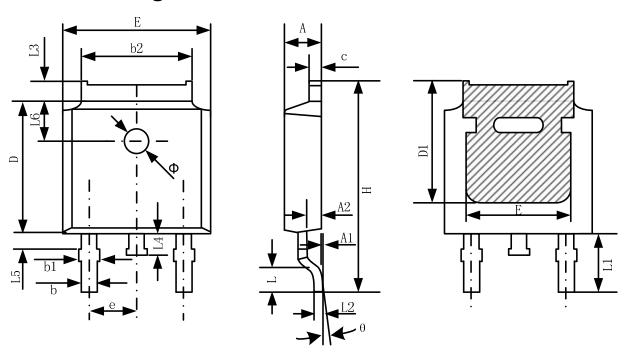
## 3) Unclamped Inductive Switching Test Circuit & Waveforms







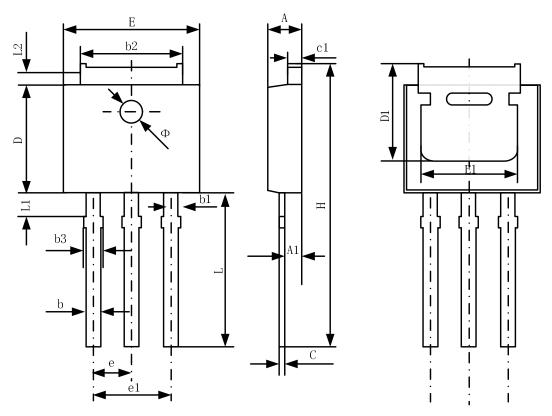
# **TO-252-2 Package Information**



Cumab at	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.20	2.38	0.087	0.094	
A1	0.00	0.10	0.000	0.004	
A2	0.90	1.10	0.035	0.043	
b	0.72	0.85	0.028	0.033	
b1	0.72	0.90	0.028	0.035	
b2	5.13	5.46	0.202	0.215	
С	0.47	0.60	0.019	0.024	
D	6.00	6.20	0.236	0.244	
D1	5.25		0.207		
Е	6.50	6.70	0.256	0.264	
E1	4.70		0.185		
e	2.19	2.39	0.086	0.094	
Н	9.80	10.40	0.386	0.409	
L	1.40	1.70	0.055	0.067	
L1	2.9	0 REF	0.114 REF		
L2	0.50	08 BSC	0.020 BSC		
L3	0.90	1.25	0.035	0.049	
L4	0.60	1.00	0.024	0.039	
L5	0.15	0.75	0.006	0.030	
L6	1.80 REF		0.071 REF		
Ф	1.20	1.40	0.047	0.055	
θ	0°	8°	0°	8°	



# **TO-251 Package Information**



Complete al	Dimensions	In Millimeters	Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
А	2.20	2.35	0.087	0.093
A1	0.90	1.10	0.035	0.043
b	0.56	0.69	0.022	0.027
b1	0.77	0.90	0.030	0.035
b2	5.23	5.43	0.206	0.214
b3		1.05	0.000	0.041
С	0.46	0.59	0.018	0.023
c1	0.46	0.59	0.018	0.023
D	6.00	6.20	0.236	0.244
D1	5.20		0.205	
E	6.50	6.70	0.256	0.264
E1	4.60	5.00	0.181	
e	2.24	2.34	0.088	0.092
e1	4.47	4.67	0.176	0.184
Н	16.18	16.78	0.637	0.661
L	9.00	9.60	0.354	0.378
L1	0.95	1.35	0.037	0.053
L2	0.90	1.25	0.035	0.049



## NCE65T1K2K,NCE65T1K2I

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